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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/816,980	04/02/2004	Ho-Yuan Yu	LOVO-56.DIV	2006
41066	7590 10/06/2004		EXAM	INER
	MURABITO & HAO,	BERRY, RENEE R		
	TWO NORTH MARKET STREET, THIRD FLOOR SAN JOSE, CA 95113		ART UNIT	PAPER NUMBER
			2818	
			DATE MAILED: 10/06/2004	

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)			
	10/816,980	YU			
Office Action Summary	Examiner	Art Unit			
•	Renee R Berry	2818			
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet with the c	orrespondence address			
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply If NO period for reply is specified above, the maximum statutory period w - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply be ting within the statutory minimum of thirty (30) day rill apply and will expire SIX (6) MONTHS from cause the application to become ABANDONE	nely filed s will be considered timely. the mailing date of this communication. D (35 U.S.C. § 133).			
Status					
1) Responsive to communication(s) filed on	_•				
2a) This action is FINAL . 2b) ⊠ This	action is non-final.				
3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under <i>Ex parte Quayle</i> , 1935 C.D. 11, 453 O.G. 213.					
Disposition of Claims					
4) Claim(s) 1-10 and 21-30 is/are pending in the a 4a) Of the above claim(s) is/are withdraw 5) Claim(s) is/are allowed. 6) Claim(s) 1-10 and 21-30 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/or	vn from consideration.				
Application Papers					
9) The specification is objected to by the Examine					
10)⊠ The drawing(s) filed on <u>02 April 2004</u> is/are: a)⊠ accepted or b)□ objected to by the Examiner.					
Applicant may not request that any objection to the	 				
Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Ex					
Priority under 35 U.S.C. § 119					
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority documents 2. Certified copies of the priority documents 3. Copies of the certified copies of the priority application from the International Bureau * See the attached detailed Office action for a list	s have been received. s have been received in Applicat rity documents have been receive u (PCT Rule 17.2(a)).	ion No ed in this National Stage			
American	•				
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date	4) Interview Summary Paper No(s)/Mail D 5) Notice of Informal F 6) Other:				

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DETAILED ACTION

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

Claims 1-10 and 21-30 are rejected under 35 U.S.C. 103(a) as being unpatentable over US Patent No. 6,707,095 to Chidambarrao in view of US Patent No. 6,576,516 to Blanchard.

In regards to claim 1, Chidambarrao teaches an electronic silicon device comprising: a silicon substrate comprising a planar surface; trench disposed in said planar surface of said silicon substrate, said trench comprising a wall and a bottom; silicon dioxide layer disposed on the bottom of said trench and also on a portion of said wall, said layer being terminated at a distance D below said planar surface of said silicon device at column 18, lines 1-16.

In regards to claim 3, Chidambarrao teaches the electronic silicon device of Claim 1, further comprising a junction field effect transistor (JFET) at column 7, lines 35-51.

In regards to claim 4, Chidambarrao teaches the electronic silicon device of Claim 1, further comprising a metal oxide semiconductor field effect transistor (MOSFET) at column 7, lines 35-51.

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In regards to claim 5, Chidambarrao teaches the electronic silicon device of Claim 1, further comprising an integrated circuit at column 7, lines 35-51.

In regards to claim 6, Chidambarrao teaches the electronic silicon device of

Claim 1, wherein said trench is disposed above a gate at column 18, lines 42-53.

In regards to claim 7, Chidambarrao teaches the electronic silicon device of

Claim 1, wherein said trench is disposed adjacent to a source at column 18, lines 42-53.

In regards to claim 9, Chidambarrao teaches the electronic silicon device of

Claim 1, wherein said silicon dioxide layer is thermally grown at column 18, lines 11-12.

In regards to claim 10, Chidambarrao teaches the electronic silicon device of

Claim 1, wherein said silicon dioxide layer is deposited at column 18, lines 11-12.

In regards to claim 23, Chidambarrao the semiconductor device of Claim 21,

further comprising a junction field effect transistor (JFET) at column 7, lines 35-51.

In regards to claim 24, Chidambarrao the semiconductor device of Claim 21, further comprising a metal oxide semiconductor field effect transistor (MOSFET) at column 7, lines 35-51.

In regards to claim 25, Chidambarrao the semiconductor device of Claim 21, further comprising an integrated circuit at column 7, lines 35-51.

In regards to claim 26, Chidambarrao teaches the semiconductor device of Claim 21, wherein said trench is disposed above a gate structure at column 18, lines 42-53.

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In regards to claim 27, Chidambarrao teaches the semiconductor device of Claim 21, wherein said trench is disposed adjacent to a source structure at column 18, lines 42-53.

In regards to claim 29, Chidambarrao teaches the semiconductor device of Claim 21, wherein paid silicon dioxide layer is thermally grown at column 18, lines 11-12.

In regards to claim 30, Chidambarrao teaches the semiconductor device of Claim 21, wherein said silicon dioxide layer is deposited at column 18, lines 11-12.

However, Chidambarrao does not teach all the limitations of the claims.

In regards to claims 1 and 2, Blanchard teaches the electronic silicon device of Claim 1, wherein that is said polysilicon fill comprises an upper surface disposed within a distance D from said planar surface of said silicon substrate at column 9, lines 1-2.

In regards to claim 8, Blanchard teaches the electronic silicon device of Claim 1, wherein said silicon dioxide layer is between 100 angstroms and 3000 angstroms in thickness at column 4, lines 40-44.

In regards to claim 21, Blanchard teaches a semiconductor device comprising: a silicon substrate; a trench disposed in said silicon substrate, said trench comprising a wall and a bottom; a silicon dioxide layer disposed on the bottom of said trench and also on a portion of said wall, said layer being terminated below an original surface of said silicon substrate; a polysilicon fill disposed on the surface of said silicon dioxide layer and on a portion of said wall at column 8, lines 47-67

In regards to claim 22, Blanchard teaches the semiconductor device of Claim 21, wherein said polysilicon fill comprises an upper surface that is disposed between a top

surface of said silicon dioxide layer and said original surface of said silicon substrate at column 9, lines 1-2.

In regards to claim 28, Blanchard the semiconductor device of Claim 21, wherein said silicon dioxide layer is between 100 angstroms and 3000 angstroms in thickness at column 4, lines 40-44.

Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to have modified Chidambarrao to include a silicon substrate; a trench disposed in said silicon substrate, said trench comprising a wall and a bottom; a silicon dioxide layer disposed on the bottom of said trench and also on a portion of said wall, said layer being terminated below an original surface of said silicon substrate; a polysilicon fill disposed on the surface of said silicon dioxide layer and on a portion of said wall, since such a modification would result in substantially reduced on-resistance, as described in column 2, lines 28-31 of Blanchard.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Renee R Berry whose telephone number is (571) 272-1774. The examiner can normally be reached on M-F 9-5:30.

The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

RRB

September 26, 2004

PRIMARY EXAMINE